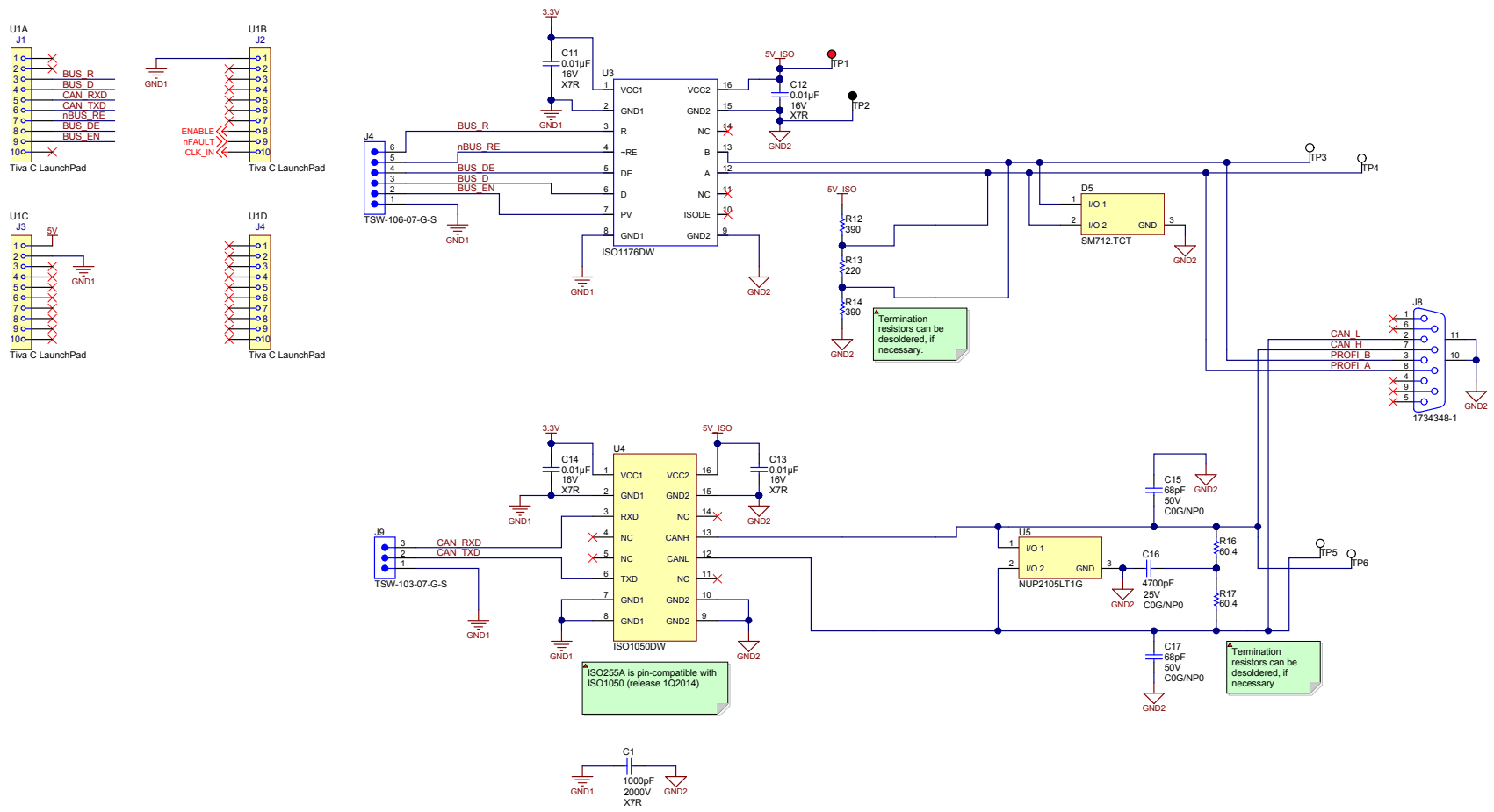


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Designed for Public Release		Mod. Date: 8/28/2013	
Project Title: High Efficiency Isolated CAN & Profibus Interface S			
Number: SAT0047	Rev: E1.1	Sheet Title: Isolated Power	Sheet: 1 of 3
SVN Rev: Not in version control	Assembly Variant: DNI	Variant	Size: B
Drawn By: Evan Cornell	File: SAT0047 Schematic Page 1.SchDoc	http://www.ti.com	
Engineer: Evan Cornell	Contact: http://www.ti.com/support	© Texas Instruments 2013	





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Project Title: High Efficiency Isolated CAN & Profibus Interface S			
Number: SAT0047	Rev: E1.1	Sheet Title: Isolated CAN & Profibus Transceivers	
SVN Rev: Not in version control	Assembly Variant: DNI Variant		Sheet 2 of 3
Drawn By: Evan Cornell	File: SAT0047_Schematic_Sheet_2_SchDoc		Size: B
Engineer: Evan Cornell	Contact: http://www.ti.com/support		http://www.ti.com
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1 2 3 4 5 6

A

A



FID1

PCB Number: SAT0047
PCB Rev: E1.1

PCB
LOGO
Texas Instruments



FID2



FID3

B

B

LBL1

PCB Label

Size: 0.65" x 0.20"

ZZ1

Label Assembly Note

This Assembly Note is for PCB labels only

C

C

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

D

D

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Designed for: Public Release		Mod. Date: 8/13/2013		
Project Title: High Efficiency Isolated CAN & Profibus Interface SI				
Number: SAT0047	Rev: E1.1	Sheet Title:		
SVN Rev: Not in version control	Assembly Variant: DNI_Variant	Sheet 3 of 3		
Drawn By:	File: Hardware_ANSI-B_Sch1Doc	Size: B		http://www.ti.com
Engineer: Evan Cornell	Contact: http://www.ti.com/support			© Texas Instruments 2013

1 2 3 4 5 6

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